Footprint information for reflow soldering of WLCSP49 package

Dimensions in mm

<table>
<thead>
<tr>
<th>P</th>
<th>SL</th>
<th>SP</th>
<th>SR</th>
<th>Hx</th>
<th>Hy</th>
</tr>
</thead>
<tbody>
<tr>
<td>0.4</td>
<td>0.24</td>
<td>0.27</td>
<td>0.31</td>
<td>3.5</td>
<td>3.5</td>
</tr>
</tbody>
</table>

Issue date: 14-11-05

solder land (SL)
solder paste deposit (SP)
solder land plus solder paste
solder resist opening (SR)
occupied area

see detail X

recommend stencil thickness: 0.1 mm

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